

FBIS-II Connector

(Floating Battery Interconnection System Connector)

Product Specification 108-61118 19AUG10 Rev. A

FBIS-2 Connector

1. Scope:

1.1 Contents

This specification covers the requirements for product performance, test methods and quality assurance provisions of FBIS-2 Connector.

Applicable product descriptions and part numbers are as shown in Appendix 2.

2. Applicable Documents:

The following documents form a part of this specification to the extent specified herein. In the event of conflict between the requirements of this specification and the product drawing, the product drawing shall take precedence. In the event of conflict between the requirements of this specification and the referenced documents, this specification shall take precedence.

2.1 AMP Specifications:

A.109-5000 Test Specification,

General Requirements for Test Methods.

B.501-61054 Test Report:

2.2 Commercial Standards and Specifications:

A. MIL-STD-202: Test Methods for Electronic and Electrical Component Parts.

B.EIA 364: Test Specification



3. Requirements

3.1 Design and Construction

Product shall be of the design, construction and physical dimensions specified on the applicable product drawing.

3.2 Materials

A. Contact

·Material: Copper Alloy

•Finish: Nickel-under plated all over.

Gold plated at contact area.

Gold flash plated at soldering area.

B. Housing

Thermoplastic Molding Compound Color: Black, UL94V-0 / UL94HB

C. Solder Peg

Material: Copper Alloy

·Finish: Nickel-under plated all over.

Tin plated all over.

3.3 Ratings

A. Voltage Rating: 30V DC

B. Current Rating: 1 A /Contact

C. Temperature Rating: -40°C to +85°C

High limit temperature includes raised temperature by operation.

3.4 Performance Requirements and Test Descriptions

The product shall be designed to meet the electrical, mechanical and environmental performance requirements specified in Fig. 1. All tests shall be performed in the room temperature, unless otherwise specified.

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3.5 Test Requirements and Procedures Summary

Para.	Test Items	Requirements	Procedures				
3.5.1	Examination of Product	Meets requirements of product	Visual inspection				
		drawing.	No physical damage				
		Electrical Requirements	S				
3.5.2	Termination Resistance	50m Ω Max. (Initial)	Subject mated contacts assembled in				
	(Low Level)	ΔR 10m Ω Max.(Final)	housing to 20 mV Max. open circuit at				
			100 mA.				
			Fig.1				
			EIA 364-23				
3.5.3	Dielectric withstanding	No creeping discharge or	500VAC for 1 minute.				
	Voltage	flashover shall occur.	Test between adjacent circuits of mated				
		Current leakage: 1mA Max.	connectors.				
			EIA 364-20				
3.5.4	Insulation Resistance	100M Ω Min.	100V DC for 1 minute.				
			Test between adjacent circuits of mated				
			connectors.				
			EIA 364-21				
3.5.5	Temperature Rising	30°C Max. under loaded rating	Measure temperature rising by energized				
		current.	current.				
			EIA 364-70 Method 2				
		Mechanical Requiremen	ts				
3.5.6	Connector Mating Force	1Pos.: 1 N Max.	Operation Speed: 100mm/min.				
			Measure the force required to mate				
			connectors.				
			EIA 364-13				
3.5.7	Connector Un-mating	1Pos.: 0.1 N Min.	Operation Speed: 100mm/min.				
	Force		Measure the force required to unmate				
			connectors.				
			EIA 364-13				
3.5.8	Durability	ΔR 10m Ω Max. (Final)	Operation Speed: 600cycles/hour Max.				
	(Repeated Mating /		Number of Cycles: 5,000 cycles (M/C Test)				
	Un-mating)		EIA 364-9				
3.5.9	Vibration	No electrical discontinuity	Mated connectors to 10-55-10 Hz traversed				
	(Low Frequency)	greater than 1 μ sec. shall	in 1 minute at 1.52mm amplitude 2 hours				
		occur.	each of 3 mutually perpendicular planes.				
		Δ R 10m Ω Max.	100mA applied.				
			EIA 364-28 Condition I				

Fig. 1 (CONT.)

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Para.	Test Items	Requirements	Procedures				
3.5.10	Physical Shock	No electrical discontinuity greater	Accelerated Velocity: 490m/s ² (50G)				
		than 1 μ sec.	Waveform: Half sin				
		shall occur.	Duration: 11m sec.				
		ΔR 10m Ω Max.	Number of Drops:3 drops each to normal				
			and reversed directions				
			of X, Y and Z axes,				
			totally 18 drops.				
			100mA applied.				
			EIA 364-27 Method A				
3.5.11	Solder ability	Wet Solder Coverage:	Solder Temperature : 230 ± 5 °C				
		90 % Min.	Immersion Duration : 3 ± 0.5 sec.				
			Flux: Alpha 100				
			EIA 364-52				
	,	Environmental Requireme	nts				
3.5.12	Thermal Shock	Δ R 10m Ω Max.	Mated connector				
			-40°C /30min. 85°C /30 min.				
			Make this a cycle, repeat 24 cycles.				
			EIA 364-32				
3.5.13	Temperature Life	ΔR 10m Ω Max.	Mated connector				
	(Heat Aging)		85°C, Duration : 96 hours				
			EIA 364-17				
3.5.14	Humidity, Steady State	ΔR 10m Ω Max.	Subject mated connector				
		Insulation Resistance	90% Min.RH, 60℃ 96hours				
		100M Ω Min.	Measure after leaving 4hour in the room				
		Dielectric Resistance Voltage	temperature & humidity.				
		To meet the spec 3.5.3.	EIA 364—31 Method II, Condition B				
3.5.15	Salt Spray	ΔR 10m Ω Max.	Mated connectors with 5 %, 35°C				
		No corrosion that damages	concentration for 48 hours.				
		function of connector allowed.	EIA 364-26 Condition B				
3.5.16	Industrial Gas (SO2)	Δ R 10m Ω Max.	Mated connector				
		No corrosion that damages	SO2 Gas: 10ppm, 75 % R. H.				
		function of connector allowed.	40°C, 48 hours				
			AMP Spec. 109-5107 Condition C				
3.5.17	Resistance to	No physical damage shall occur.	Soldering iron Temperature:380±10°C				
	Soldering Heat		5sec. Max. No Pressurize a Tine.				
			EIA 364-56				
3.5.18	Resistance to Reflow	No physical damage allowed.	Temperature profile; as shown in Fig. 3				
	Heat		EIA 364-56				

Fig. 1 (End)

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3.6 Product Qualification Test Sequence

	Test Group									
Test Examination	1	2	3	4	5	6	7	8	9	10
	Test Sequence (a)									
Examination of Product	1,7	1,10	1,6	1,6	1,10	1,6	1,6	1,4	1,3	1,3
Termination Resistance (Low Level)	3,6	3,9	3,5	3,5	3,9	3,5	3,5			
Dielectric withstanding Voltage					5,8					
Insulation Resistance					4,7					
Temperature Rising								3		
Vibration (Low Frequency)	4									
Physical Shock	5									
Connector Mating Force		4,7								
Connector Un-mating Force		5,8								
Durability (Repeated Mate / Un-mating)		6								
Solderability									2	
Thermal Shock			4							
Temperature Life (Heat Aging)				4						
Humidity (Steady State)					6					
Salt Spray						4				
Industrial SO ₂ Gas							4			
Resistance to Soldering										2
Resistance to Reflow Heat	2	2	2	2	2	2	2	2		

Appendix 1

The applicable product descriptions and part numbers are as shown in Appendix.2.

Product Part No.	Description			
x-2108074-x	FBIS-II RECEPTACLE CONNECTOR			
x-2108070-x	EDIC II DI LIC COMMECTOD			
x-2108078-x	FBIS-II PLUG CONNECTOR			

Appendix 2

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⁽a) Numbers indicate sequence in which the tests are performed.

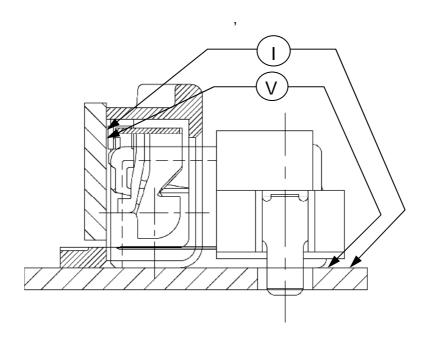
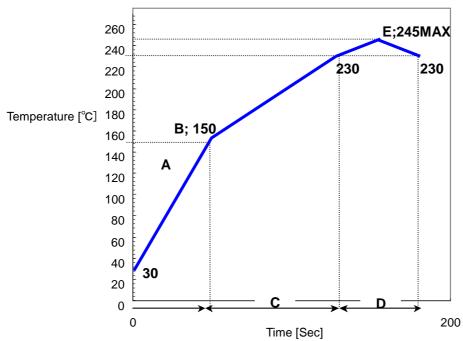


Fig.1 Termination Resistance Measuring Points



	Condition
A: The Speed of Temperature Rising	0.5~2.0°C/sec
B: The Start Temperature of Pre-Heating	150∼200°C
C: Time of Pre-Heating	60~100 sec
D:Time of upper 230 °C	45~60 sec
E:Temperature of Peak Point	245°C

% Number of Reflow times; 2 times.

Fig.3 Temperature profile for Reflow.

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